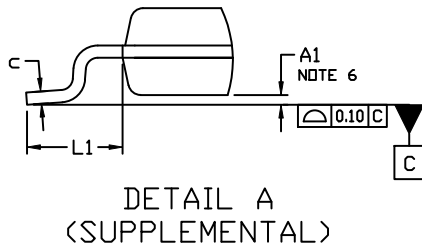
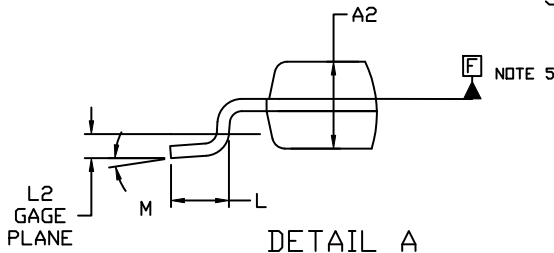
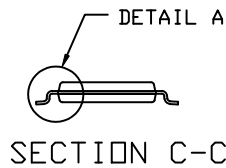
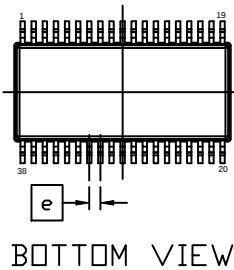
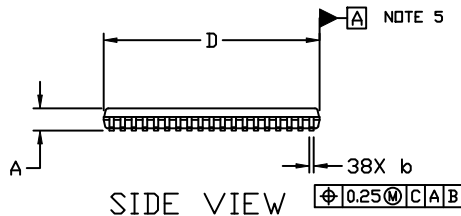
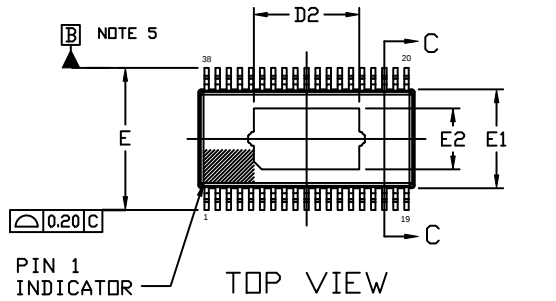


TSSOP38 TEP 9.7x4.4
CASE 948BX
ISSUE O

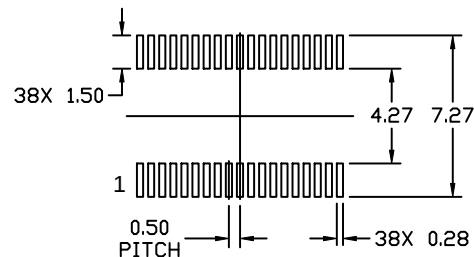
DATE 01 FEB 2021



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.127 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM F.
5. DATUMS A AND B ARE TO BE DETERMINED AT DATUM F.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
7. LEAD THICKNESS (c) AND LEAD WIDTH (b) INCLUDE PLATING THICKNESS.

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	---	---	1.10
A1	0.05	---	0.15
A2	0.85	---	0.95
b	0.17	---	0.27
c	0.09	---	0.20
D	9.60	9.70	9.80
D2	4.496	---	4.852
E	6.25	6.40	6.55
E1	4.30	4.40	4.50
E2	2.489	---	2.845
e	0.50 BSC		
L	0.50	---	---
L1	1.00 REF		
L2	0.25 REF		
M	0°	---	8°



RECOMMENDED
MOUNTING FOOTPRINT

- * For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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